LOADPOINT

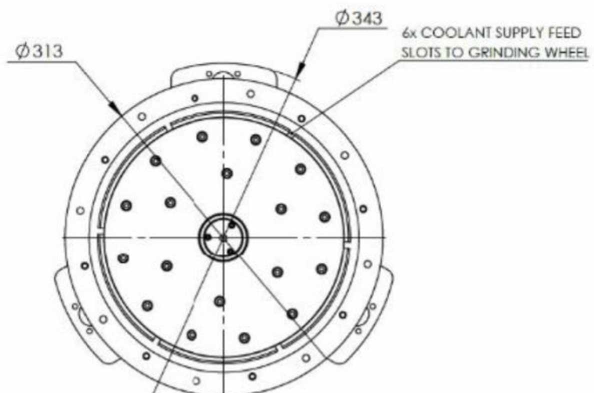
WAFER BACK GRINDING SPINDLE

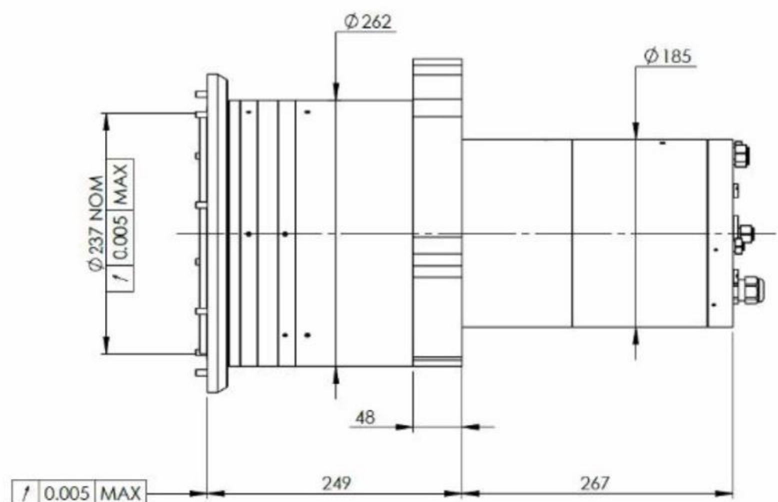
11082

FOR 12" WAFERS

FOR GRINDING SEMICONDUCTOR AND OPTICAL MATERIALS

Speed Range	1000—4,000 rpm
Motor Power	6.3 kw (11 kw)
Air Supply Pressure	5.5 bar
Bearing Air Consumption	80 l/min
Axial Stiffness	82 kg/um
Axial Failure Load	> 1530 N
Radial Runout at Tool	≤ 3 um
Axial Runout at Tool	≤ 3 um
Motor Type	Brushless DC
Weight (Approx)	156 kg
Body Diameter (nominal)	262 mm





OUR DESIGN AND DEVELOPMENT EXPERIENCE PLACES US IN THE IDEAL POSITION TO DEVELOP NEW AIR BEARING PRODUCTS AND APPLICATIONS.

AVAILABLE IN A RANGE OF CONFIGURATIONS.

ASSOCIATED SPINDLE SPEEDS TO SUIT APPLICATION.

ENHANCED SPINDLE WITH:

- HIGH RIGIDITY
- MINIMAL VIBRATION
- LOW HEAT EXPANSION
- MINIMAL ROTATIONAL SPEED FLUCTUATION
- BI-DIRECTIONAL ROTATION
- THROUGH SHAFT COOLANT

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